

AMENDMENTS TO THE CLAIMS

1. **(Currently Amended)** A photosensitive resin plate comprising a support having formed thereon directly or via an adhesive layer a photosensitive layer of from 0.45 to 0.8 mm in thickness comprising a negative working photosensitive resin composition consisting essentially of

- (A) a film-forming polymer,
- (B) an unsaturated compound having a radical polymerizable ethylenic double bond,
- (C) a photopolymerization initiator in an amount of 0.5 - 5 wt% based on the weight of the photosensitive resin composition components (A) to (E),
- (D) a thermal polymerization inhibitor, and
- (E) at least one member selected from compounds represented by following formula (I):



wherein -X represents -OR², -COOH, [[-SO₃H,]] -CONHR², -COR², -HNCONHR², or -HNCOOR²; R¹ and R², which may be the same or different, each represents a hydrogen atom, a substituted or unsubstituted, saturated or unsaturated hydrocarbon group, provided that it does not contain a radical polymerizable ethylenic double bond, a substituted or unsubstituted alicyclic hydrocarbon group, a substituted or unsubstituted aromatic hydrocarbon group, or a heterocyclic group, wherein said hydrocarbon group, alicyclic hydrocarbon group, aromatic hydrocarbon group, or the heterocyclic group may have an ether bond in the chain, provided that when -X is -OH, the R¹ represents a group other than a hydrogen atom and an aromatic hydrocarbon group, provided that component (E) is not benzophenone and is different from component (C), in an amount of from 0.001 to 0.3% by weight based on the weight of the photosensitive resin composition components (A) to (E).

2. **(Original)** The photosensitive resin plate as claimed in claim 1, wherein the compound represented by the formula (I) has a boiling point of at least 95°C.

3. **(Original)** The photosensitive resin plate as claimed in claim 1, wherein the component (A) is at least one member selected from water-soluble polymers, alkali-soluble polymers, and alcohol-soluble polymers.

4. (Original) A photosensitive resin plate having formed thereon photocured images obtained by selectively exposing the photosensitive layer on the photosensitive resin plate as claimed in claim 1 through a mask pattern, developing, and forming the photocured images by removing the unexposed areas.